电弧离子镀弧斑运动对膜层质量影响分析

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摘 要:随着薄膜材料在现代工业中的广泛应用,电弧离子镀技术已成为制备功能性膜层的重要方法,在航空航天方面主要面向于功能表面改性、复合材料表面金属化等领域。本文采用磁场控制电弧离子镀靶材表面的弧斑运动,在 Ti 靶上验证了弧斑在不同磁场下的运动状态,分析了弧斑的运动速度及运动范围。在五种磁场情况下制备 TiN 膜层,通过扫描电镜、能谱分析仪、台阶仪、X 射线衍射仪等对 TiN 膜层的表面形貌、微观结构、成分元素、膜层厚度等进行了分析。结果发现,当磁场控制弧斑均匀地分布在整个Ti 靶面,且弧斑运动速度加快时,膜层表面大颗粒数最少,膜层最厚,晶体择优生长方向为(111)晶面。

关键词:电弧离子镀;弧斑;磁场;膜层分析

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Analysis of Influence of Cathode Spot Movement on Film Quality in Arc Ion Plating Technology

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Abstract: With the wide application of thin film materials in modern industry, arc ion plating technology has become an important method for preparing functional films, such as functional surface modification and surface metallization of composite materials in the field of aerospace. In order to verify the state of cathode spot movement under different magnetic fields, the cathode spot on Ti target was controlled by magnetic field. TiN films were prepared under five magnetic fields, and the surface morphology, microstructure, chemical composition and thickness of TiN film were detected and analyzed through scanning electron microscope, energy disperse spectroscopy, step profiler and X-ray diffractometer. The results show that the film has the least number of large particles, the film is the thickest, and the crystal preferential growth direction is (111) crystal plane, when the cathode spot controlled by the magnetic field is uniformly distributed on the entire Ti target surface and the cathode spot movement speed increased.

Key words: arc ion plating; cathode spot; magnetic field; film analysis

目前,电弧离子镀技术成为制备功能性膜层的重要方法,其具有离子能量高、沉积速率快、绕镀性好、膜 – 基结合力高、膜层致密、离化率高(60%~90%)[1-3]的技术优点,在切削业、模具工业、机械制造、航空航天等行业得到了普遍的应用[4-6]。此外,利用电弧离子镀技术成功加快了热控涂层、碳纤维表面金属化的研究进展,尤其在航天事业迅猛发展的大形势下,电弧离子镀技术更显重要。

在广泛应用的同时,电弧离子镀技术也存在

着一些技术问题,阻碍了其进一步发展。如何提升电弧离子镀膜层的质量,是研究者一直在解决的问题,影响膜层质量的因素包括真空室本底真空、工作温度、靶材质量、工作气体流场等,其中最为迫切的就是改善甚至消除膜层的大颗粒(Macro-particles, MPS)污染问题[2,7-9]。电弧离子镀膜技术主要依靠靶面上的弧斑放电来获得沉积膜层所需的膜料。弧斑作为一种点状的微型蒸发源,其运动轨迹对大颗粒污染问题具有重要的影响。当弧斑长期处于某一局部区域,会对该局部